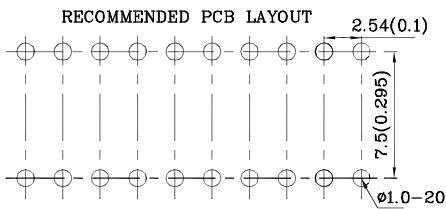
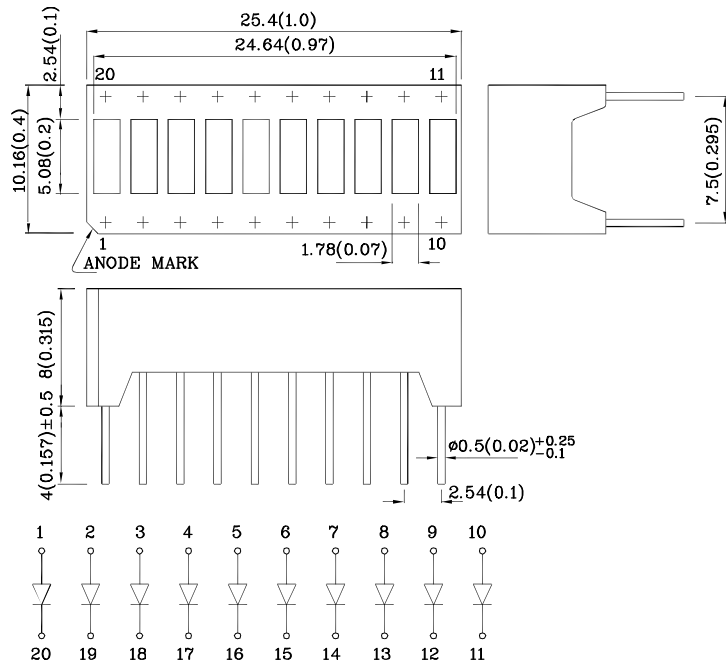


### Features

- Robust package
- Uniform light disbursement
- Ideal for backlighting logos or icons
- Excellent for flush mounting
- Standard configuration: Gray face w/ white segments
- RoHS compliant



### Package Schematics



#### Notes:

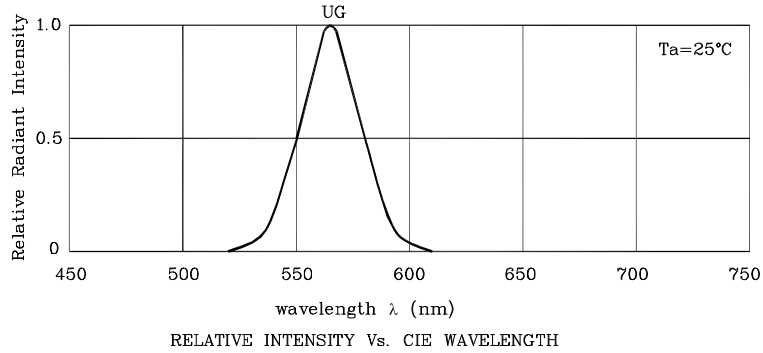
1. All dimensions are in millimeters (inches), Tolerance is  $\pm 0.25(0.01)$  unless otherwise noted.
2. Specifications are subject to change without notice.

Absolute Maximum Ratings ( $T_A=25^\circ\text{C}$ )		UG (GaP)	Unit
Reverse Voltage	$V_R$	5	V
Forward Current	$I_F$	25	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	$i_{FS}$	140	mA
Power Dissipation	$P_D$	62.5	mW
Operating Temperature	$T_A$	-40 ~ +85	°C
Storage Temperature	$T_{stg}$	-40 ~ +85	
Lead Solder Temperature [2mm Below Package Base]	260°C For 3-5 Seconds		

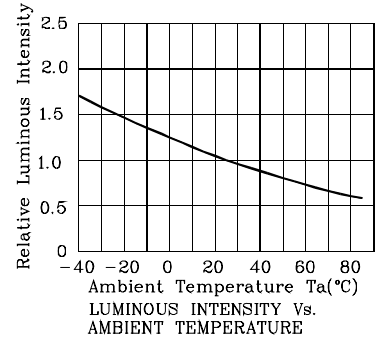
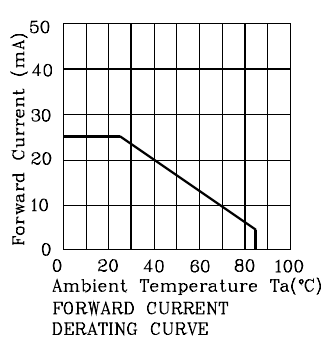
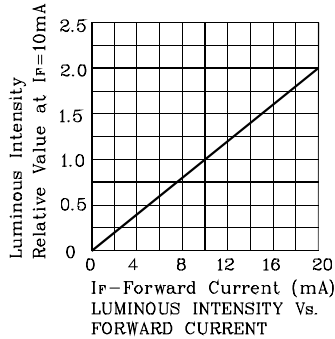
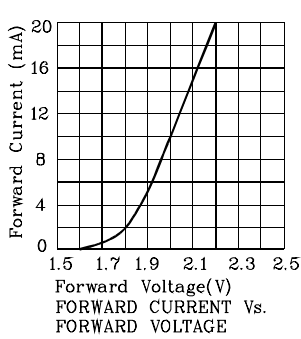
Operating Characteristics ( $T_A=25^\circ\text{C}$ )		UG (GaP)	Unit
Forward Voltage (Typ.) ( $I_F=10\text{mA}$ )	$V_F$	2	V
Forward Voltage (Max.) ( $I_F=10\text{mA}$ )	$V_F$	2.5	V
Reverse Current (Max.) ( $V_R=5\text{V}$ )	$I_R$	10	$\mu\text{A}$
Wavelength of Peak Emission CIE127-2007* (Typ.) ( $I_F=10\text{mA}$ )	$\lambda_P$	565*	nm
Wavelength of Dominant Emission CIE127-2007* (Typ.) ( $I_F=10\text{mA}$ )	$\lambda_D$	568*	nm
Spectral Line Full Width At Half-Maximum (Typ.) ( $I_F=10\text{mA}$ )	$\Delta\lambda$	30	nm
Capacitance (Typ.) ( $V_F=0\text{V}$ , $f=1\text{MHz}$ )	C	15	pF

Part Number	Emitting Color	Emitting Material	Luminous Intensity CIE127-2007* ( $I_F=10\text{mA}$ ) ucd		Wavelength CIE127-2007* nm $\lambda_P$	Description
			min.	typ.		
XGUGX10D	Green	GaP	5600 1400*	11990 3990*	565*	10 Segments Bar graph-Display

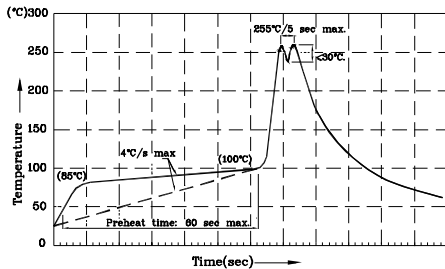
\*Luminous intensity value and wavelength are in accordance with CIE127-2007



❖ UG



Wave Soldering Profile for Thru-Hole Products (Pb-Free Components)



- Notes:
1. Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260°C
  2. Peak wave soldering temperature between 245°C ~ 255°C for 3 sec (5 sec max).
  3. Do not apply stress to the epoxy resin while the temperature is above 85°C.
  4. Fixtures should not incur stress on the component when mounting and during soldering process.
  5. SAC 305 solder alloy is recommended.
  6. No more than one wave soldering pass.

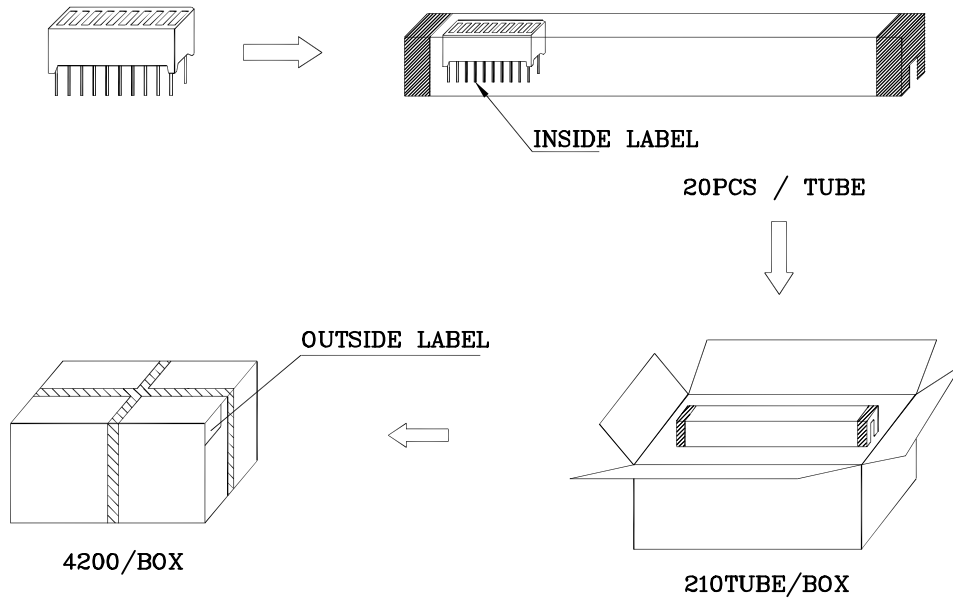
Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

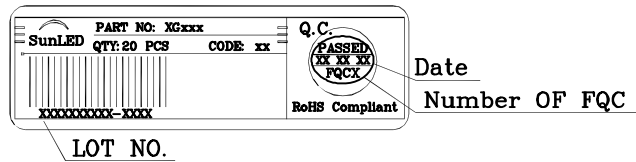
1. Wavelength: +/-1nm
2. Luminous Intensity / Luminous Flux: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

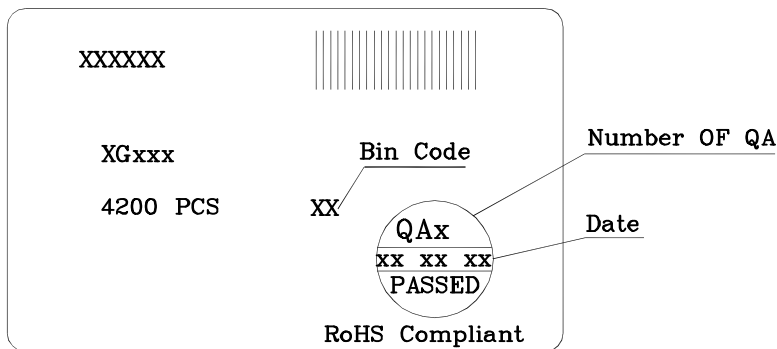
**PACKING & LABEL SPECIFICATIONS**



**Inside Label On IC-tube**



**Outside Label On Box**



**TERMS OF USE**

1. Data presented in this document reflect statistical figures and should be treated as technical reference only.
2. Contents within this document are subject to improvement and enhancement changes without notice.
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